

Global 3D IC and 2.5D IC Packaging Market Professional Survey Report 2018

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Abstracts

This report studies 3D IC and 2.5D IC Packaging in Global market, especially in North America, China, Europe, Southeast Asia, Japan and India, with production, revenue, consumption, import and export in these regions, from 2012 to 2016, and forecast to 2022.

This report focuses on top manufacturers in global market, with production, price, revenue and market share for each manufacturer, covering

Taiwan Semiconductor

Samsung Electronics

Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

On the basis of product, this report displays the production, revenue, price, market share and growth rate of each type, primarily split into

3D wafer-level chip-scale packaging

3D TSV

2.5D

By Application, the market can be split into

Logic

Imaging & optoelectronics

Memory

MEMS/sensors

LED

Power

By Regions, this report covers (we can add the regions/countries as you want)

North America

China

Europe

Southeast Asia

Japan

India

If you have any special requirements, please let us know and we will offer you the report as you want.

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